

#### Description

The IRFR024NPBF uses advanced trench

technology to provide excellent R<sub>DS(ON)</sub>, low gate

charge and operation with gate voltages as low

as 4.5V. This device is suitable for use as a

Battery protection or in other Switching application.

### **General Features**

V<sub>DS</sub> = 60V I<sub>D</sub> =20 A

 $R_{DS(ON)} < 32m\Omega @ V_{GS}=10V$ 

### Application

Battery protection

Load switch

Uninterruptible power supply

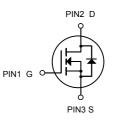
### Package Marking and Ordering Information

	Product ID	Pack	Brand	Qty(PCS)
ſ	IRFR024NPBF	TO-252-2L	HXY MOSFET	2500

### Absolute Maximum Ratings (Tc=25°Cunless otherwise noted)

Symbol	Parameter	Rating	
Vds	Drain-Source Voltage	/oltage 60	
Vgs	Gate-Source Voltage	±20	V
I₀@Tc=25°C	Continuous Drain Current, VGS @ 10V1	20	A
I <b>⊳@T</b> c=100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	10	А
Ідм	Pulsed Drain Current <sup>2</sup>	Ised Drain Current <sup>2</sup> 80	
EAS	Single Pulse Avalanche Energy <sup>3</sup>	38	mJ
P₀@Tc=25°C	Total Power Dissipation <sup>4</sup>	34.7	W
Тѕтс	Storage Temperature Range	torage Temperature Range -55 to 150	
TJ	Operating Junction Temperature Range	-55 to 150	°C





N-Channel MOSFET

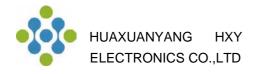


### **Electrical Characteristics (T**J = 25°C, unless otherwise noted)

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static Characteristics		1	1		1	1		
Drain-Source Breakdown Vo	oltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250µA	60 -		-	V	
Gate-Body Leakage Curren	Gate-Body Leakage Current		Icss V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V		-	±100	nA	
Zero Gate Voltage Drain	TJ=25℃			-	-	1	μA	
Current	TJ=100℃	- I <sub>DSS</sub>	$V_{DS} = 60V, V_{GS} = 0V$	-	-	100		
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS}$ = $V_{GS}$ , $I_D$ = 250 $\mu$ A	1.2	1.7	2.5	V	
		_	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	25	32	mΩ	
Drain-Source on-Resistance	<u>j</u> 4	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5A	-	31.5	40		
Forward Transconductance <sup>4</sup>		<b>g</b> fs	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A	-	15.5	-	S	
Dynamic Characteristic	<b>S</b> <sup>5</sup>				L			
Input Capacitance		Ciss		-	1355	-		
Output Capacitance		C <sub>oss</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> =0V, f =1MHz	-	60	-	pF	
Reverse Transfer Capacitar	се	Crss		-	49	-		
Gate Resistance		Rg	f =1MHz	-	1.2	-	Ω	
Switching Characteristi	CS <sup>5</sup>	·					•	
Total Gate Charge		Qg		-	22	-		
Gate-Source Charge		Qgs	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 30V, I <sub>D</sub> = 10A	-	4.2	-	nC	
Gate-Drain Charge	Gate-Drain Charge			-	6.9	-		
Turn-on Delay Time		t <sub>d(on)</sub>		-	6.4	-		
Rise Time		tr	V <sub>GS</sub> =10V, V <sub>DD</sub> = 30V,	-	15.3	-	ns	
Turn-off Delay Time		t <sub>d(off)</sub>	$R_G = 3\Omega$ , $I_D = 10A$	-	25	-		
Fall Time		tr	-	-	7.6	-		
Body Diode Reverse Recovery Time		trr		-	26	-	ns	
Body Diode Reverse Recovery Charge		Qrr	l⊧=10A, dl⊧/dt=100A/µs	-	45	-	nC	
Drain-Source Body Dio	de Characte	ristics	1	<b>I</b>	L	1	1	
Diode Forward Voltage <sup>4</sup>		Vsd	I <sub>S</sub> = 10A, V <sub>GS</sub> = 0V	-	-	1.2	V	
Continuous Source Current	Tc=25℃	ls	_		_	20	A	

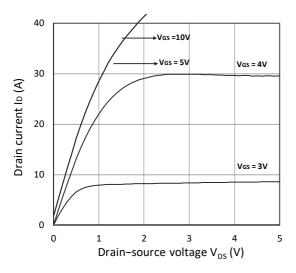
Notes:

- 1. Repetitive rating, pulse width limited by junction temperature  $T_{J(\text{MAX})}\text{=}150^\circ\text{C}$
- 2. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}\text{=}25V,\,V_{\text{GS}}\text{=}10V,\,L\text{=}0.4\text{mH},\,I_{\text{AS}}\text{=}14\text{A}$
- 3. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
- 4. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%.
- 5. This value is guaranteed by design hence it is not included in the production test.



## IRFR024NPBF N-Channel Enhancement Mode MOSFET

### **Typical Characteristics**





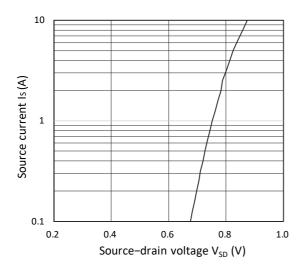


Figure 3. Forward Characteristics of Reverse

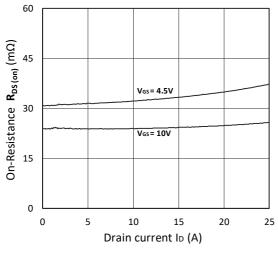


Figure 5.  $R_{\text{DS}(\text{ON})}$  vs.  $I_{\text{D}}$ 

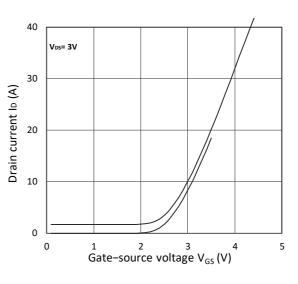
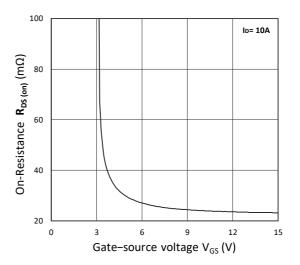


Figure 2. Transfer Characteristics





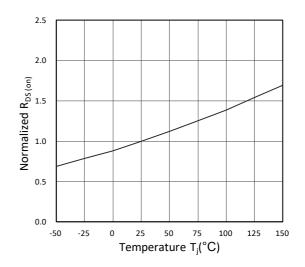
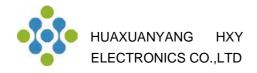
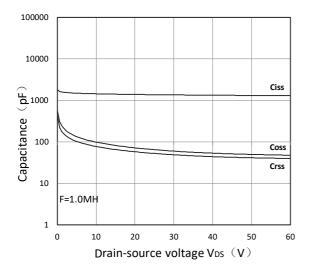
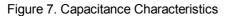


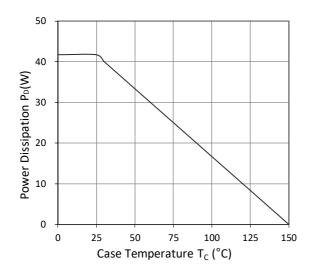
Figure 6. Normalized  $R_{DS(on)}$  vs. Temperature



### IRFR024NPBF N-Channel Enhancement Mode MOSFET









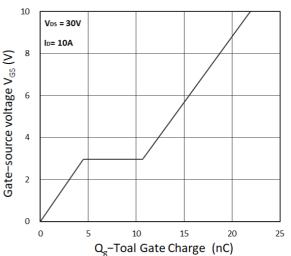
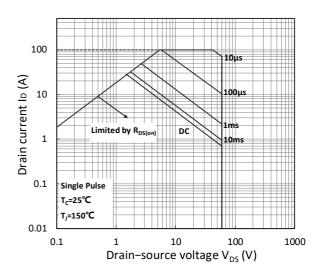
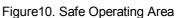
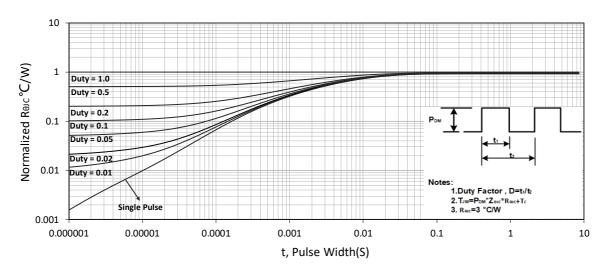
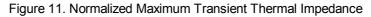


Figure 8. Gate Charge Characteristics



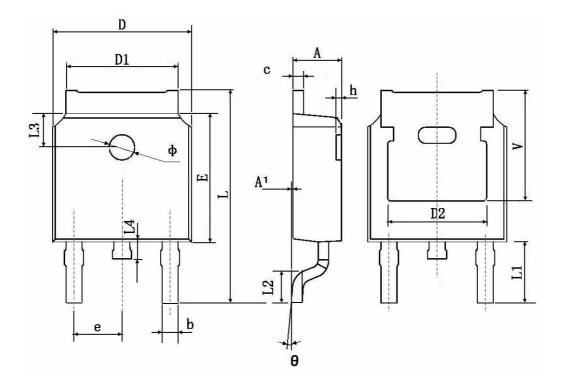








### **TO-252-2L Package Information**



Ormited	Dimensions	In Millimeters	Dimensions In Inches			
Symbol	Min.	Max.	Min.	Max.		
A	2.200	2.400	0.087	0.094		
A1	0.000	0.127	0.000	0.005		
b	0.660	0.860	0.026	0.034		
с	0.460	0.580	0.018	0.023		
D	6.500	6.700	0.256	0.264		
D1	5.100	5.460	0.201	0.215		
D2	0.483 TYP.		0.190 TYP.			
E	6.000	6.200	0.236	0.244		
е	2.186	2.386	0.086	0.094		
L	9.800	10.400	0.386	0.409		
L1	2.900	2.900 TYP.		0.114 TYP.		
L2	1.400	1.700	0.055	0.067		
L3	1.600 TYP.		0.063 TYP.			
L4	0.600	1.000	0.024	0.039		
Φ	1.100	1.300	0.043	0.051		
θ	0°	8°	0 °	8°		
h	0.000	0.300	0.000	0.012		
V	5.350 TYP. 0.211 TYP.			TYP.		



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